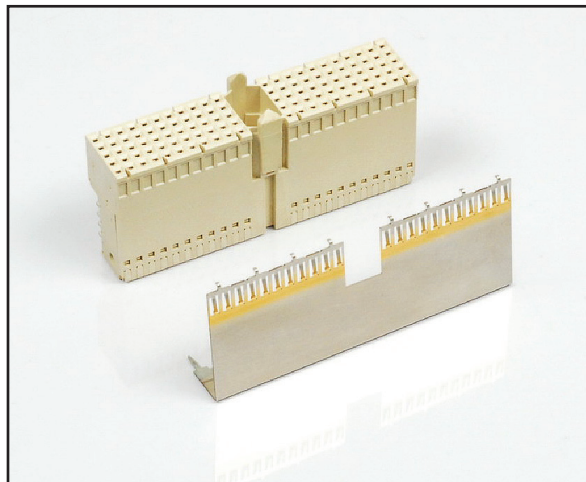


3M™ CP2 Press-Fit Socket

2 mm Type A 110 Signal Contacts Right Angle

CP2 Series



- 25 mm basic system unit
- 50 mm module
- Designed according to IEC 61076-4-101 and IEC 60352-5 Standards
- 2 mm grid spacing allows for high signal density at low cost
- “Eye of the Needle” compliant pin press-fit design reduces manufacturing time and cost
- Additional grounding row available for improved ground bounce and EMI immunity
- Mates with 5 row 3M™ HM, and CP2 Headers
- End-to-end stackable with 5 row 3M™ HSHM, UHM, and CP2 Sockets
- See the Regulatory Information Appendix (RIA) in the “RoHS compliance” section of www.3Mconnectors.com for compliance information (RIA E1 & C1 apply)

Date Modified: July 16, 2015

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Physical

Insulation:

Material: High Temperature Thermoplastic (LCP)
Flammability: UL94V-0

Contact:

Material: Copper Alloy
Plating: See Ordering Information

Mechanical

Mating Force: $\leq 0.75\text{N/PIN}$
Withdrawl Force: $\geq 0.15\text{N/PIN}$
Mating and Un-mating Operations: 200 for KR plating

Electrical

Current Rating: 1.0 Amperes at 70°C with all contacts powered
Contact Resistance: $\leq 20\text{ m}\Omega$
Insulation Resistance: $\geq 10,000\text{ M}\Omega$
Test Voltage: 750 VAC_{RMS}

Environmental

Temperature Ratings: -55°C to +125°C

PCB Data

Recommended PCB Plated Through Hole: $\text{Ø } 0.6 \pm 0.05\text{ mm}$
Drill Hole Diameter: $\text{Ø } 0.7 \pm 0.02\text{ mm}$
Hole platings: Cu 25~50 μm , Sn < 10 μm
PCB thickness: 1.4 - 4.2 mm
Press-In Force: $\leq 204\text{N/pin}$ on nominal hole diameter
Retention Force: $\geq 13.5\text{N/pin}$ on nominal hole diameter



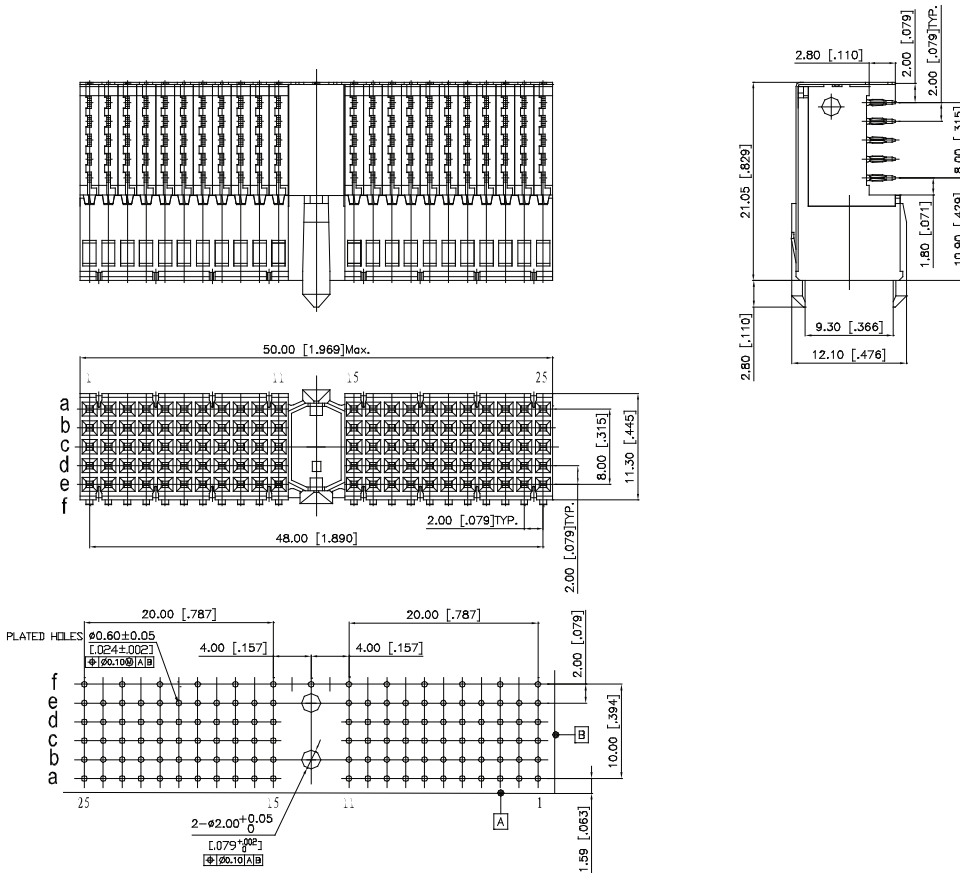
Electronics Materials Solutions Division
Interconnect Solutions
<http://www.3Mconnectors.com>

For technical, sales or ordering information call
800-225-5373

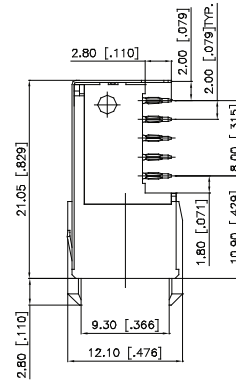
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Recommended PCB Layout



Tolerance Unless Noted			
	±0.	±.0	±.00
mm	±1	±0.3	±0.13

[] Dimensions for Reference only

Ordering Information

CP2-SA110-X1-XXXX

Shield Options
 G= Upper Shield
 Blank= No Shield

Plating Options

- FJ= 10~20 μ" Gold Contact Area
 100~200 μ" Matte Tin
 50~80 μ" Nickel Underplate
 (RIA E1 & C1 apply)
- KR= 30~40 μ" Gold Contact Area
 100~200 μ" Matte Tin
 50~80 μ" Nickel Underplate
 (RIA E1 & C1 apply)

• This diagram serves only for Part Number descriptive definitions.
 PLEASE CONTACT YOUR LOCAL SALES REPRESENTATIVE FOR CUSTOMER SPECIFIC PRODUCT CONFIGURATIONS.

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 Sheet 2 of 2



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